W, H, McL & N Dacket No.____

Declaration For U.S. Patent Application

As a below named inventor, I hereby declare that:

M	y residence,	post	office address	and	l citizenship	are	as stated	below	v next to my	name.
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	d below) of the subject matter	which is claimed	and for which a patent i	an original, first and joint inventous sought on the invention entitled MBRYONIC ANTIGENS					
			GAR CHAIN STRU						
the specification	n of which is attached hereto u	nless the follow	ing is checked:						
	was filed on		as United States Application Number or PCT International						
	Application Number		and was amended on						
ld	(if applicable).								
	hat I have reviewed and unders nent referred to above.	tand the content	s of the above-identified	specification, including the claim	n(s), as amended				
I acknowledge	the duty to disclose information	which is materi	al to patentability as defir	ned in Title 37, Code of Federal Re	egulations, § 1.56.				
inventor's certi		so identified bel	ow any foreign application	(d) of any foreign application(s) to for patent or inventor's certific	ate having a fil-				
(List prior	11-172485		Japan	18/June/1999	Priority Claimed _				
(List prior foreign	(Numbe	r)	(Country)	(Day/Month/Year Filed)					
applications. See note A on back of	(Number	r)	(Country)	(Day/Month/Year Filed)	Yes No Yes No				
this page)	(Number	r)	(Country)	(Day/Month/Year Filed)					
	(Number	r)	(Country)	(Day/Month/Year Filed)	_ • Yes • No				
(See note B on	back of this page)	☐ See attached	list for additional prior f	oreign applications					
I hereby claim	the benefit under Title 35, Unit	ted States Code,	§ 119(e) of any United S	States provisional application(s) li	sted below.				
	(Applic	ation Number)		(Filing Date)					
	(Applic	ation Number)		(Filing Date)	-				
subject matter of the first paragraity as defined i	of each of the claims of this ap aph of Title 35, United States C	plication is not o Code, § 112, I ac gulations, § 1.56	lisclosed in the prior Uni knowledge the duty to di which became available	tes application(s) listed below and ted States application in the manuscribe information which is mate between the filing date of the pri	ner provided by rial to patentabil-				
(List Prior U Applications)		al Number)	(Filing Date)	(Status) (patented, pending, abandoned) (Status) (patented, pending, abandoned)					
	(Application Seria	al Number)	(Filing Date)						

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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Inventor's Signat	ture	Date				
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Residence		Citizenship				
Post Office Addre	ress					
Full name of seve	venth inventor (given name, family name)					
Inventor's Signat	ventor's SignatureDate					
ResidenceCitizenship						
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Inventor's SignatureDate						
	ress					